

COORSTEK
Amazing Solutions.®



**THICK-FILM PHOTO
ETCHING**



semiconductor



thermal



mechanical



wear



fluid



electronic

THICK-FILM ETCHING TECHNOLOGIES FOR ALL OF YOUR ADVANCED APPLICATIONS

Photo Etching

Thick-Film Ceramic Technologies
Ultra-Fine-Line Applications

Description

Our ultra-fine photo etching, used primarily for high-frequency and high-speed applications, achieves extremely high-resolution lines and spaces. Specially formulated pastes with high-conductivity and high-back-lit density make up the base conductor layer used for etching.

Features

- Lines and spaces down to 25 micron (0.001").
- Tight control of critical conductor patterns; 25 micron ± 2.5 micron (0.001" ± 0.0001 ").
- Etching can be combined with standard thick-film processes such as vias, resistors, dielectrics, and typical screen-printed conductors.
- Performance similar to thin film while using lower cost standard thick-film application techniques.

Metals Used for Base Layer

Gold and silver etchable materials will be recommended based on the product design and function. The most frequently used materials are high in metal density, conductivity, and rate excellent for bondability. Please contact our Thick-Film Specialist for more information.

Substrate Materials

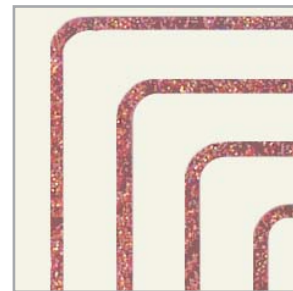
- Alumina 96%, 99.5%, 99.6%
- LTCC

Just the Tip...

This capability is only a small sample of the CoorsTek offering. Contact your sales representative to learn more about our technical ceramics, engineered plastics, and services like lapping, laser-machining, and laboratory testing.



25 micron (0.001")
418x Magnification



32.5 micron (0.0013")
380x Magnification



50 micron (0.002")
380x Magnification

